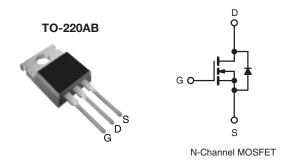
HALOGEN FREE



# **E Series Power MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700				
R <sub>DS(on)</sub> max. at 25 °C (Ω)	V <sub>GS</sub> = 10 V 0.28				
Q <sub>g</sub> max. (nC)	96				
Q <sub>gs</sub> (nC)	11				
Q <sub>gd</sub> (nC)	21				
Configuration	Single				



### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C<sub>iss</sub>)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

## **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	SiHP15N65E-E3			
Lead (Pb)-free and Halogen-free	SiHP15N65E-GE3			

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	650	V	
Gate-Source Voltage			$V_{GS}$	± 30	1 v	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	\/ ot 10 \/	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I <sub>D</sub>	15	А	
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		10		
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	38		
Linear Derating Factor				1.4	W/°C	
Single Pulse Avalanche Energy b			E <sub>AS</sub>	286	mJ	
Maximum Power Dissipation			$P_{D}$	34	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope T <sub>J</sub> = 125 °C		dV/dt	37	)//		
Reverse Diode dV/dt <sup>d</sup>			23	- V/ns		
Soldering Recommendations (Peak Temperature) c for 10 s				300	°C	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 4.5 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .



# Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W		
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.7			

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> :	= 0 V, I <sub>D</sub> = 250 μA	650	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.75	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
		V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30 \text{ V}$		-	_	± 1	μA
			= 650 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 8 A	-	0.23	0.28	Ω
Forward Transconductance	9fs	V <sub>DS</sub>	= 30 V, I <sub>D</sub> = 8 A	-	5.6	-	S
Dynamic		•					
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	1640	-	_
Output Capacitance	Coss	1	$V_{DS} = 100 \text{ V},$	-	80	-	
Reverse Transfer Capacitance	C <sub>rss</sub>	7	f = 1 MHz	-	4	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>			-	63	-	pF
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>	V <sub>DS</sub> = 0 \	$V_{DS} = 0 \text{ V to } 520 \text{ V}, V_{GS} = 0 \text{ V}$		213	-	
Total Gate Charge	$Q_g$		$V_{GS} = 10 \text{ V}$ $I_D = 8 \text{ A}, V_{DS} = 520 \text{ V}$		48	96	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V			11	-	
Gate-Drain Charge	Q <sub>gd</sub>	1			21	-	
Turn-On Delay Time	t <sub>d(on)</sub>	•		-	18	36	
Rise Time	t <sub>r</sub>	Vpp	$V_{DD} = 520 \text{ V}, I_D = 8 \text{ A}, V_{GS} = 10 \text{ V}, R_q = 9.1 \Omega$		24	48	no
Turn-Off Delay Time	t <sub>d(off)</sub>				48	96	ns
Fall Time	t <sub>f</sub>			-	25	50	
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		-	0.8	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	•
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	38	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 8 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 8 A, dl/dt = 100 A/µs, V <sub>R</sub> = 400 V		-	325	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	4.6	-	μC
Reverse Recovery Current	I <sub>RRM</sub>				20		A

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

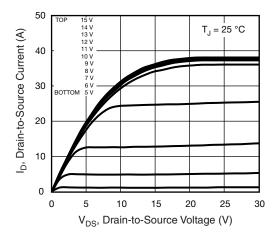


Fig. 1 - Typical Output Characteristics

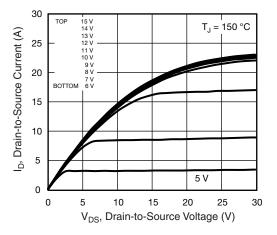


Fig. 2 - Typical Output Characteristics

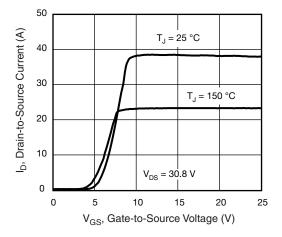


Fig. 3 - Typical Transfer Characteristics

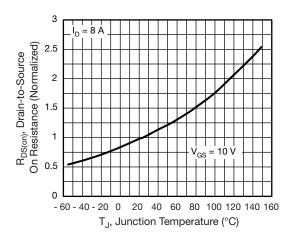


Fig. 4 - Normalized On-Resistance vs. Temperature

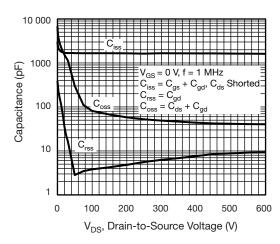


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

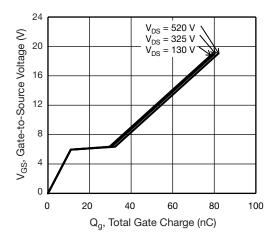


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



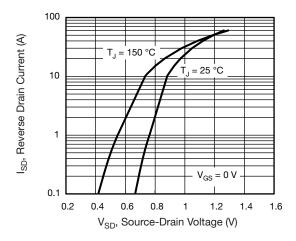


Fig. 7 - Typical Source-Drain Diode Forward Voltage

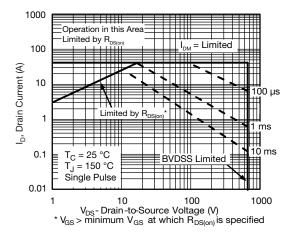


Fig. 8 - Maximum Safe Operating Area

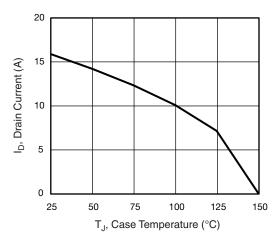


Fig. 9 - Maximum Drain Current vs. Case Temperature

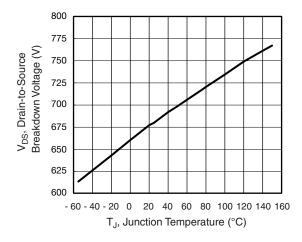


Fig. 10 - Temperature vs. Drain-to-Source Voltage

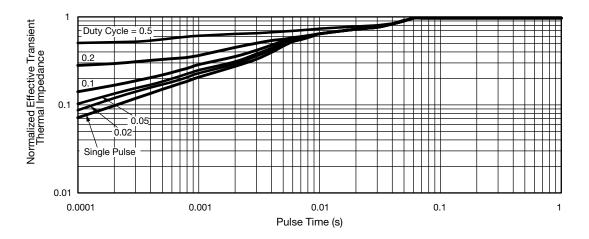


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



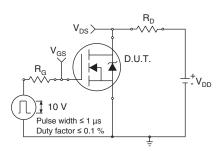


Fig. 12 - Switching Time Test Circuit

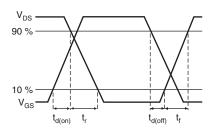


Fig. 13 - Switching Time Waveforms

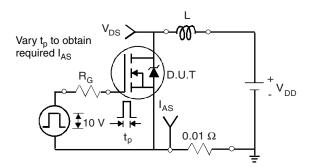


Fig. 14 - Unclamped Inductive Test Circuit

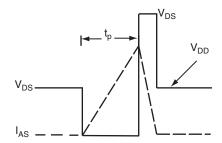


Fig. 15 - Unclamped Inductive Waveforms

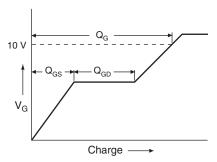


Fig. 16 - Basic Gate Charge Waveform

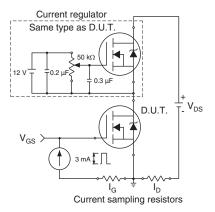
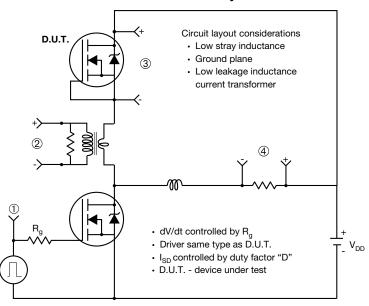


Fig. 17 - Gate Charge Test Circuit



# Peak Diode Recovery dV/dt Test Circuit



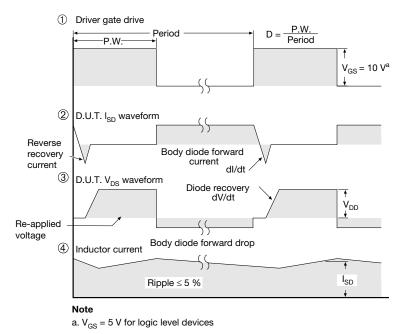
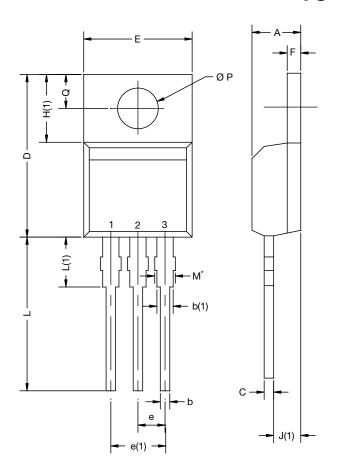


Fig. 18 - For N-Channel

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# TO-220-1



DIM.	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØΡ	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

## Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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